NOTES

1. MATERIALS:
   LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.005
   BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QUIK-PAK FOR DETAILS.

2. FINISH:
   LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1,
   GOLD PLATE PER MIL-G-45204, TYPE S, GRADE A, CLASS 1
   BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)

3. PACKAGE MISMATCH: BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.

4. UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES
   AND CORNERS = 0.25mm MAX.

5. PACKAGE CONFORMS TO JEDEC MO-220

DIMENSIONS ARE IN MILLIMETERS
TOLERANCES ARE:
   ANGULAR: ±0.5 degree
   .X = ±0.25
   .XX = ±0.13
   .XXX = ±0.01

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DRAWN: D. Abbe
CHECKED: S. Savin
ENG APPR: S. Savin

SCALE: 1:1
WEIGHT:

NOTE 1: SEE NOTE 1
NOTE 2: SEE NOTE 2

SHEET 1 OF 1

QP-QFN20-5MM-0.65MM